

Chemical content 74LV1T00GW



Type number	Package	Package description	Total product weight
74LV1T00GW	SOT353-1	UMT5	5.48725 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935690114125	5	1	260	30 s	1	240	20 s	3	Seremban, Malaysia; Bangkok, Thailand; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	0.00729	75.00000	0.13285
	Polymer	Resin system	Proprietary	0.00243	25.00000	0.04428
		subTotal		0.00972	100.00000	0.17713
Die	Doped silicon	Silicon (Si)	7440-21-3	0.07216	100.00000	1.31497
		subTotal		0.07216	100.00000	1.31497
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	1.90775	96.84000	34.76692
		Iron (Fe)	7439-89-6	0.04551	2.31000	0.82932
		Lead (Pb)	7439-92-1	0.00020	0.01000	0.00359
		Phosphorous (P)	7723-14-0	0.00138	0.07000	0.02513
		Zinc (Zn)	7440-66-6	0.00236	0.12000	0.04308
	Pure metal layer	Silver (Ag)	7440-22-4	0.01280	0.65000	0.23336
		subTotal		1.97000	100.00000	35.90140
Mould Compound	Filler	Silica -amorphous-	7631-86-9	1.09068	35.07000	19.87657
		Silica fused	60676-86-0	1.36342	43.84000	24.84713
	Pigment	Carbon black	1333-86-4	0.00778	0.25000	0.14169
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	0.31100	10.00000	5.66768
		Phenol Formaldehyde resin (generic)	9003-35-4	0.30913	9.94000	5.63368
		Polyethylene (PE) -wax-	9002-88-4	0.02799	0.90000	0.51009
		subTotal		3.11000	100.00000	56.67684
Post-Plating	Impurity	Antimony (Sb)	7440-36-0	0.00001	0.00300	0.00017
		Bismuth (Bi)	7440-69-9	0.00000	0.00100	0.00006
		Copper (Cu)	7440-50-8	0.00000	0.00100	0.00006
		Lead (Pb)	7439-92-1	0.00002	0.00500	0.00028
	Tin solder	Tin (Sn)	7440-31-5	0.30997	99.99000	5.64890
		subTotal		0.31000	100.00000	5.64947
Wire	Impurity	Non hazardous	Proprietary	0.00000	0.01000	0.00003
	Pure metal	Copper (Cu)	7440-50-8	0.01537	99.99000	0.28011
		subTotal		0.01537	100.00000	0.28014

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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